

DZ2J160

Silicon epitaxial planar type

For constant voltage / For surge absorption circuit

■ Features

- Excellent rising characteristics of zener current I_Z
- Low zener operating resistance R_Z
- Halogen-free / RoHS compliant
(EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

■ Marking Symbol: XJ, XU

■ Packaging

DZ2J160×0L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Repetitive peak forward current	I_{FRM}	200	mA
Total power dissipation *1	P_T	200	mW
Electrostatic discharge *2	ESD	±8	kV
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

Note) *1: Mounted on glass epoxy print board. (45 mm × 45 mm × 1 mm)

Solder in (Recommended land pattern)

*2: Test method: IEC61000-4-2 (C = 150 pF, R = 330 Ω, Contact discharge: 10 times)

■ Common Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 10 \text{ mA}$			1.0	V
Zener voltage *1, 2, 4	V_Z	$I_Z = 5 \text{ mA}$	15.30		16.80	V
Zener operating resistance	R_Z	$I_Z = 5 \text{ mA}$			50	Ω
Zener rise operating resistance	R_{ZK}	$I_Z = 0.5 \text{ mA}$			80	Ω
Reverse current	I_R	$V_R = 12 \text{ V}$			0.05	μA
Temperature coefficient of zener voltage *3	S_Z	$I_Z = 5 \text{ mA}$		14.2		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 5 MHz.

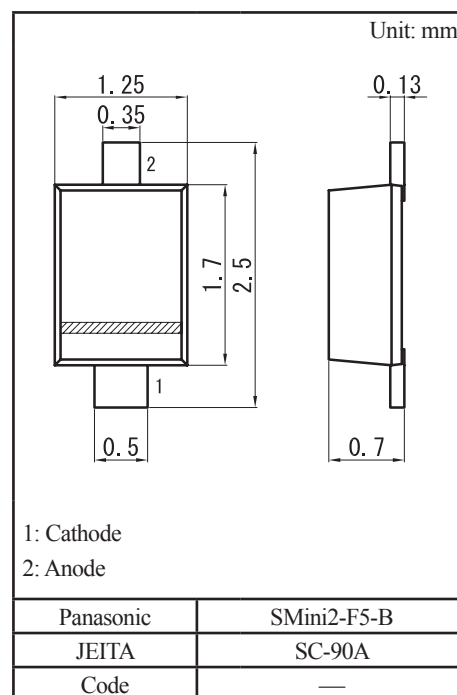
3. *1: The temperature must be controlled 25°C for V_Z measurement. V_Z value measured at other temperature must be adjusted to $V_Z(25^\circ\text{C})$

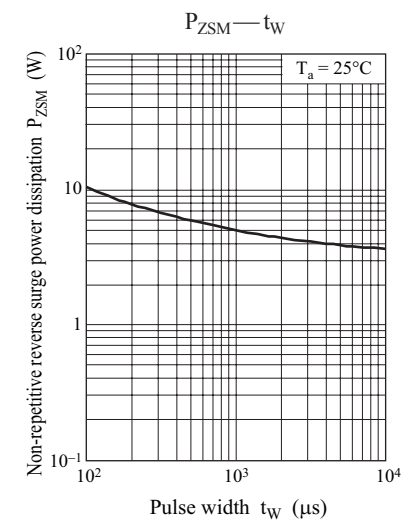
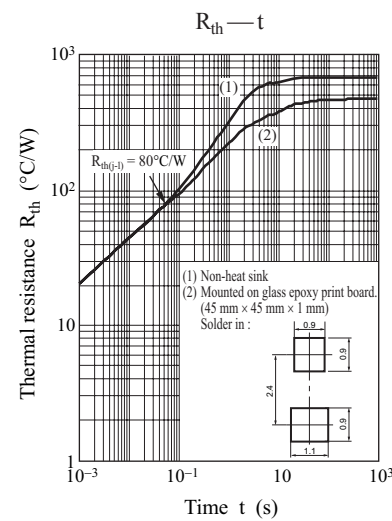
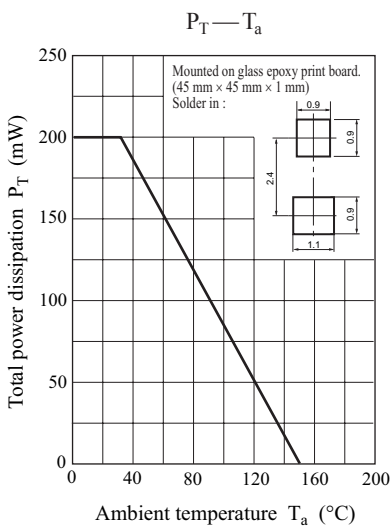
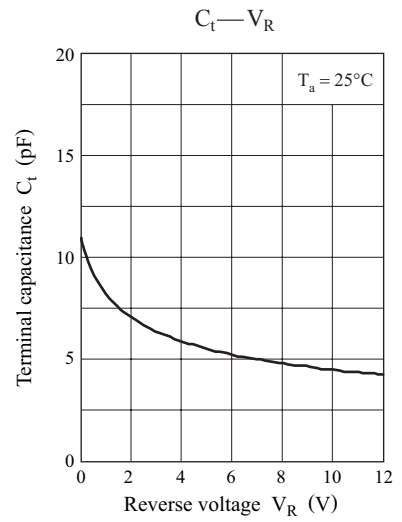
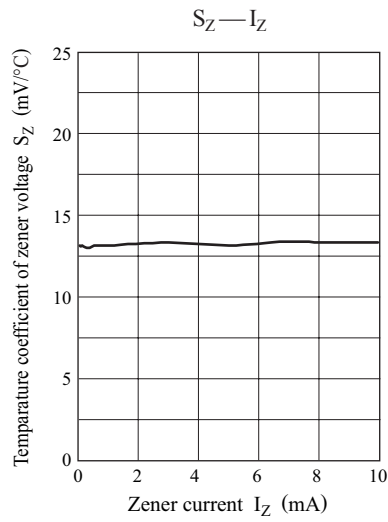
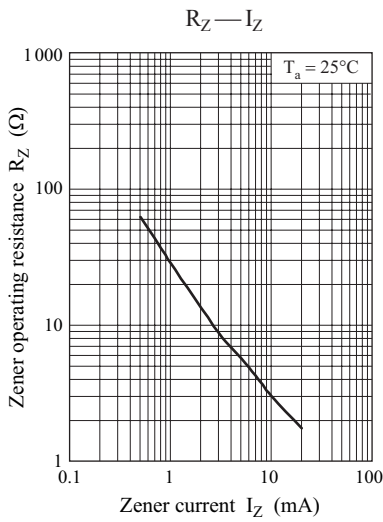
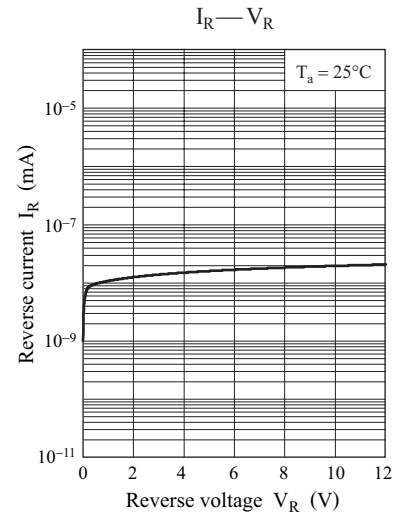
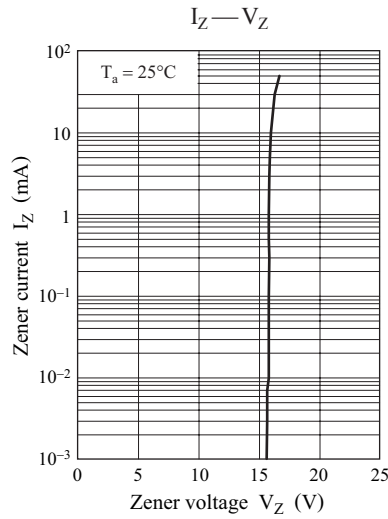
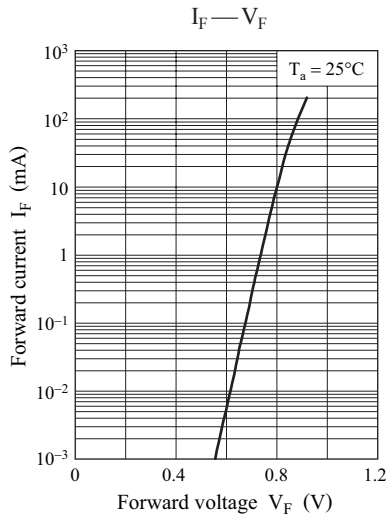
*2: V_Z guaranteed 20 ms after current flow.

*3: $T_j = 25^\circ\text{C}$ to 150°C

*4: Rank classification

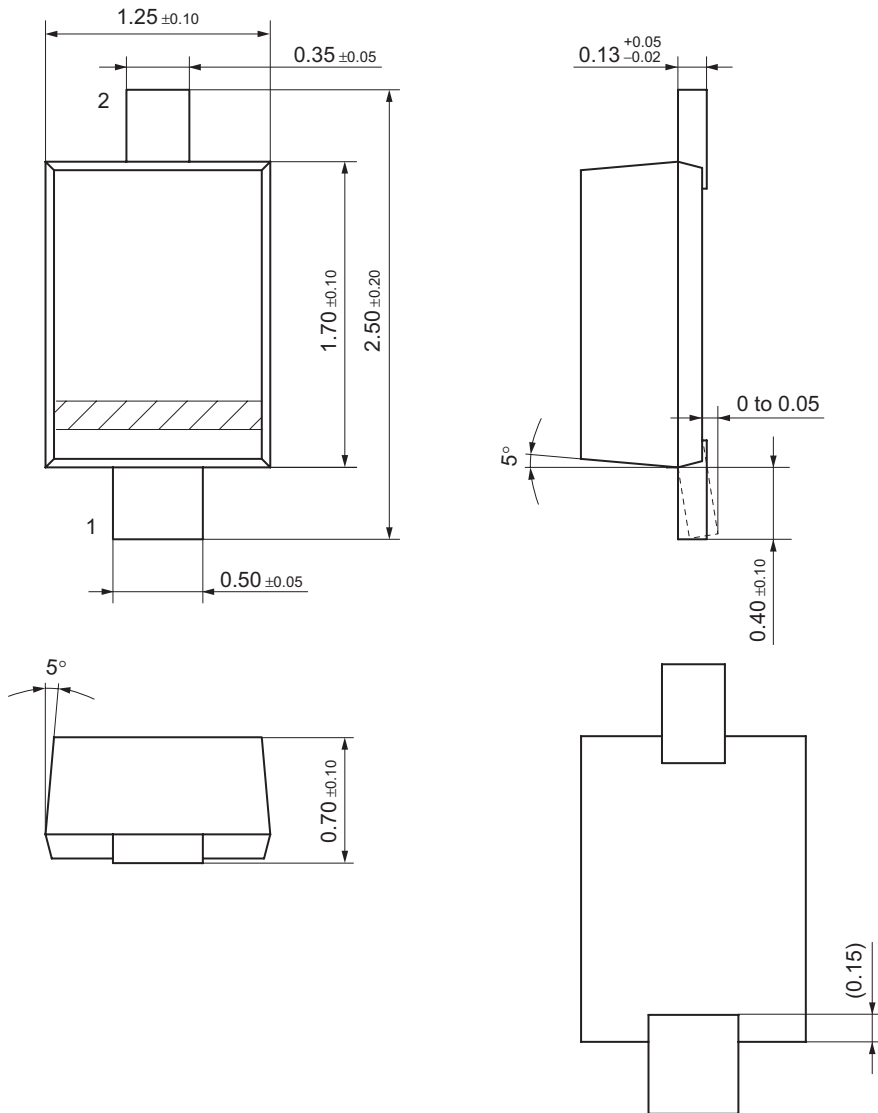
Code	M	0
Rank	M	No-rank
V_Z	15.70 to 16.50	15.30 to 16.80
Marking Symbol	XU	XJ



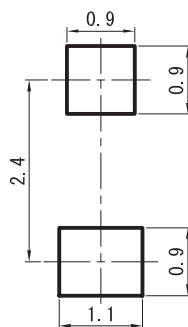


SMini2-F5-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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